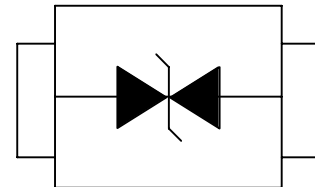


RoHS Device
Halogen Free

Features

- IEC61000-4-2 ESD 30KV Air, 30KV contact compliance
- SOD-323 surface mount package
- Protects bi-directional line
- Working voltage: 3.3V
- Low leakage current
- Low clamping voltage
- Solid-state silicon avalanche technology
- Solder reflow temperature: Pure Tin-Sn, 260~270°C
- Flammability rating UL 94V-0
- Meets MSL level 1, per J-STD-020

SOD-323



Pin Configuration

Applications

- Cellular handsets & Accessories
- Cordless phones
- Personal digital assistants (PDAs)
- Notebooks & Handhelds
- Portable instrumentation
- Digital cameras
- Peripherals
- MP3 players

Maximum Ratings

Rating	Symbol	Value	Unit
Peak pulse power (tp=8/20µs waveform)	P _{PP}	500	W
Peak pulse current (tp=8/20µs waveform)	I _{PP}	25	A
ESD voltage (Contact discharge)	V _{ESD}	±30	kV
ESD voltage (Air discharge)		±30	
Storage & operating temperature range	T _{STG} , T _J	-55~+150	°C

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Reverse stand-off voltage	V_{RWM}				3.3	V
Reverse breakdown voltage	V_{BR}	$I_{BR}=1mA$	4			V
Reverse leakage current	I_R	$V_R=3.3V$			1	μA
Clamping voltage ($t_p=8/20\mu s$)	V_C	$I_{PP}=1A$			9.8	V
Clamping voltage ($t_p=8/20\mu s$)	V_C	$I_{PP}=25A$		10		V
Off state junction capacitance	C_J	0Vdc, f=1MHz		100		pF

Typical Characteristics Curves

Figure 1. Power Derating Curve

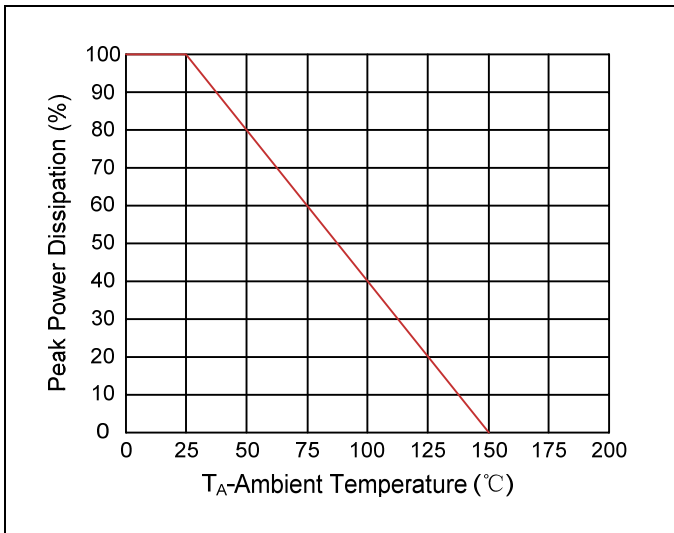


Figure 2. Pulse Waveform

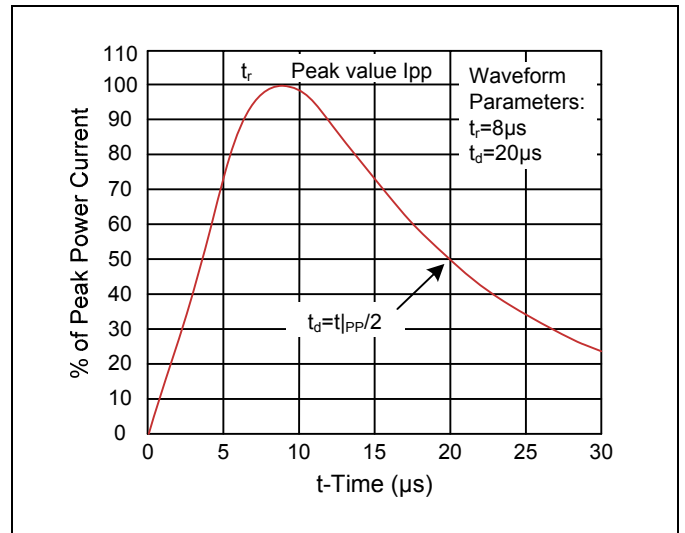
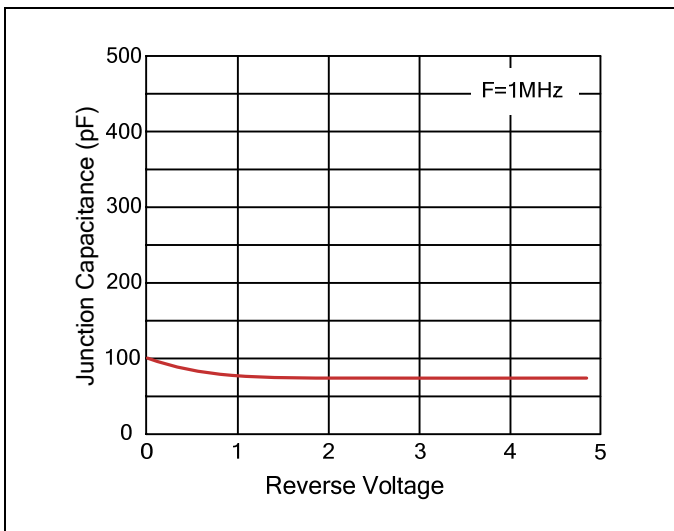
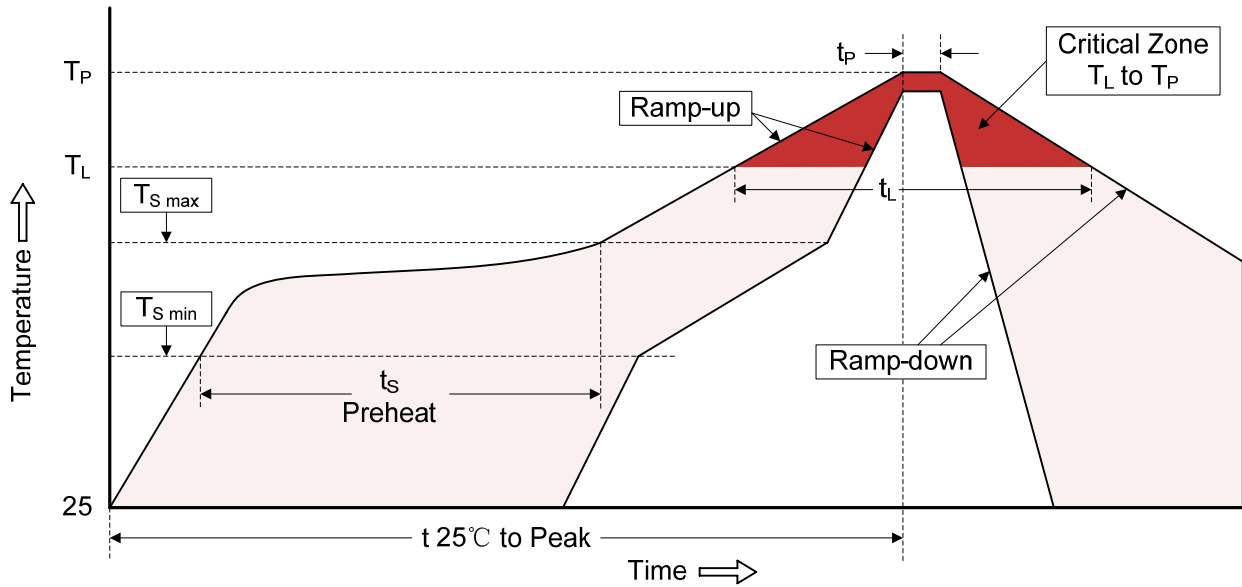


Figure 3. Capacitance vs. Reverse Voltage



Recommended Soldering Conditions

Reflow Soldering



Recommended Condition

Profile Feature	Pb-Free Assembly
Average ramp-up rate (TL to TP)	3°C/second max.
Preheat -Temperature Min (TSmin) -Temperature Max (TSmax) -Time (min to max) (ts)	150°C 200°C 60-180 seconds
TSmax to TL -Ramp-up Rate	3°C/second max.
Time maintained above: -Temperature (TL) -Time (tL)	217°C 60-150 seconds
Peak Temperature (TP)	260°C
Time within 5°C of actual Peak Temperature (tp)	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

Dimensions (SOD-323)

Symbol	Dimension			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	0.80	1.10	0.031	0.043
B	-	0.10	-	0.004
C	0.20	-	0.008	-
D	0.11	0.20	0.004	0.008
E	1.15	1.35	0.045	0.053
F	-	0.35	-	0.014
G	1.60	1.80	0.063	0.071
H	2.40	2.60	0.094	0.102

Recommended Soldering Pad Layout

Packaging

Tape	Symbol	Dimension (mm)
	W	8.00±0.30
	P0	4.00±0.10
	P1	4.00±0.10
	P2	2.00±0.10
	D0	Φ1.55±0.10
	D1	Φ1.00±0.05
	E	1.75±0.10
	F	3.50±0.10
	A	1.48±0.10
	A0	0.80±0.10
	B	3.00±0.10
	B0	1.80±0.10
	K	1.05±0.10
	t	0.25±0.05

Reel	Symbol	Dimension (mm)
	D	Φ178.0±2.0
	D2	Φ13.0
	W1	9.5
	Quantity: 3000PCS	